



Desire
For
Innovation

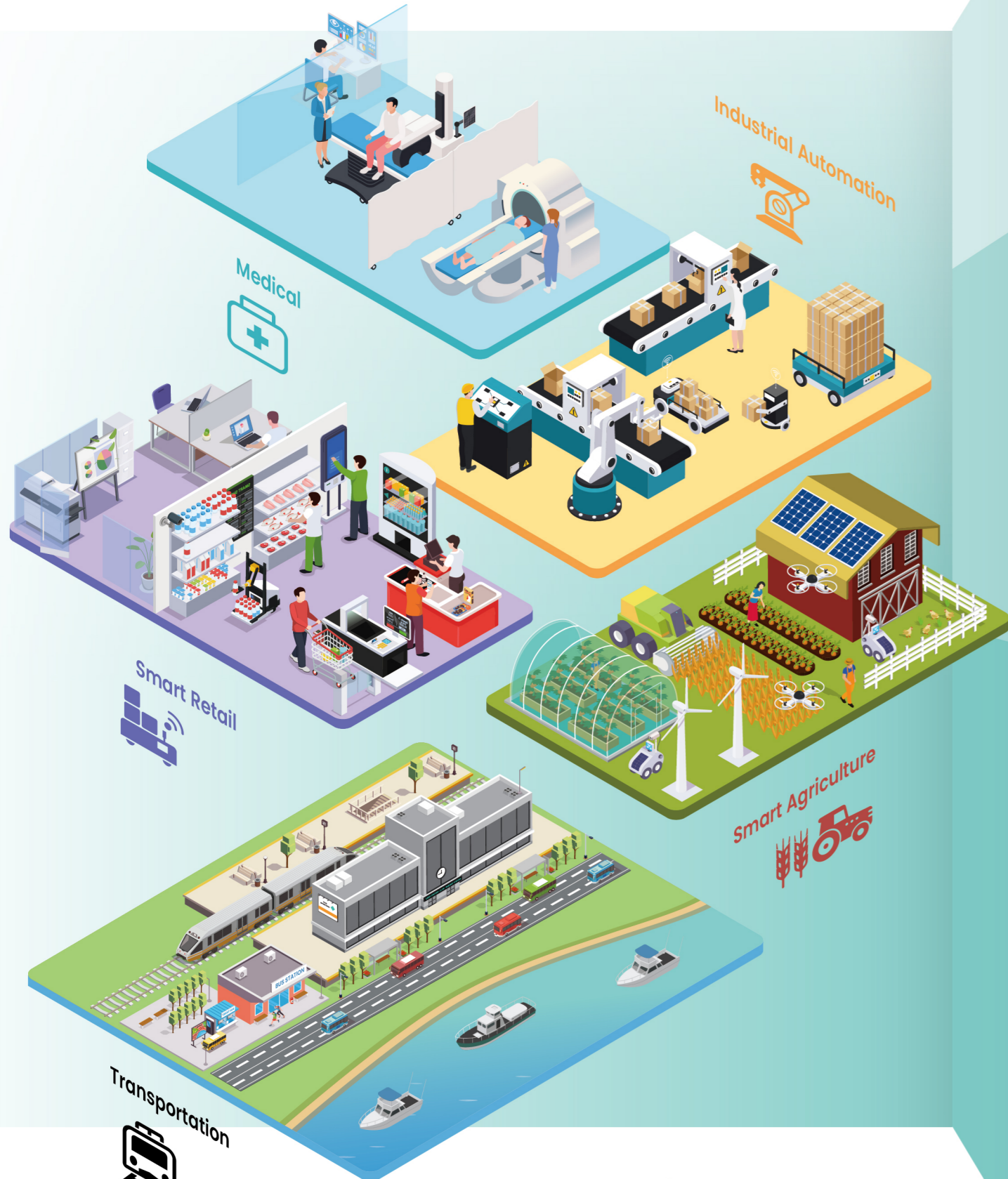


Fueling the Growth of Edge AI Computing

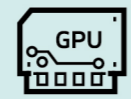
Diverse and Flexible Edge AI Computing Solutions
Driving Unstoppable Innovation

Empowering AI at the Edge – The Expert in Edge AI Computing Solutions

DFI's edge AI computing solutions drive innovation across various industries by providing real-time, secure, cost-effective platforms, and energy-efficient performance, alongside DFI's out-of-band (OOB) management to ensure reliable operations.



- 1,000,000 Boards/Year
Supplying 1 million boards annually
- 10,000,000
Powering 10 million machines globally
- 15 Years
Up to 15 years of longevity for Intel products



Intelligence Solutions with Powerful & Scalable GPU Computing



NVIDIA® Jetson Orin™ NX



Edge AI Box

Intel® Core™ Ultra



Edge AI Box

Intel® Core™



In-Vehicle AI System

Intel® Core™



Medical Grade AI Platform

Intel® Core™



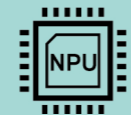
4U Edge Server

Intel® Core™



Railway AI System

Industrial Embedded Systems with MXM / PEG / NVIDIA® Jetson Orin™



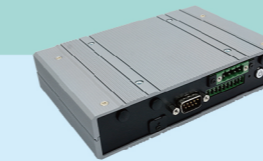
NPU-Integrated Solutions for AI Tasking on x86 & Arm Architectures



Intel® Core™ Ultra



Qualcomm Platforms



NVIDIA® Jetson Orin™ NX



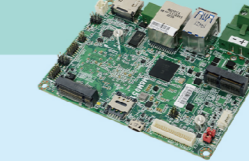
AMD Ryzen™



Intel® Core™ Ultra



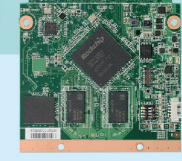
NXP Platforms



Qualcomm Platforms



Intel® Core™ Ultra / NXP / Rockchip



AI-Ready System

AI-Ready SBC

AI-Ready SoM



Edge AI Computing Solutions with the Latest Computing Platforms



Intel® Core™



Compact Fanless System

Intel® Core™



Performance Compact PC

Intel® Core™



Embedded Fanless Computing System

Intel® Core™



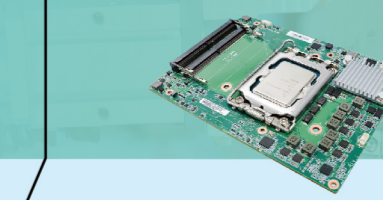
Expandable Fanless Embedded System

Intel® Core™ / AMD Ryzen™



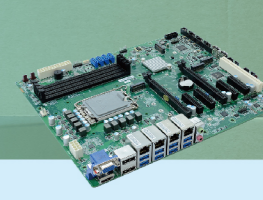
4" / 3.5" / 2.5" / 1.8" SBC

Intel® Core™ / Intel® Xeon® /
AMD Ryzen™



COM Express Mini, Compact, Basic /
COM HPC / Qseven /
SDM SoM

Intel® Core™ / Intel® Xeon® /
AMD Ryzen™



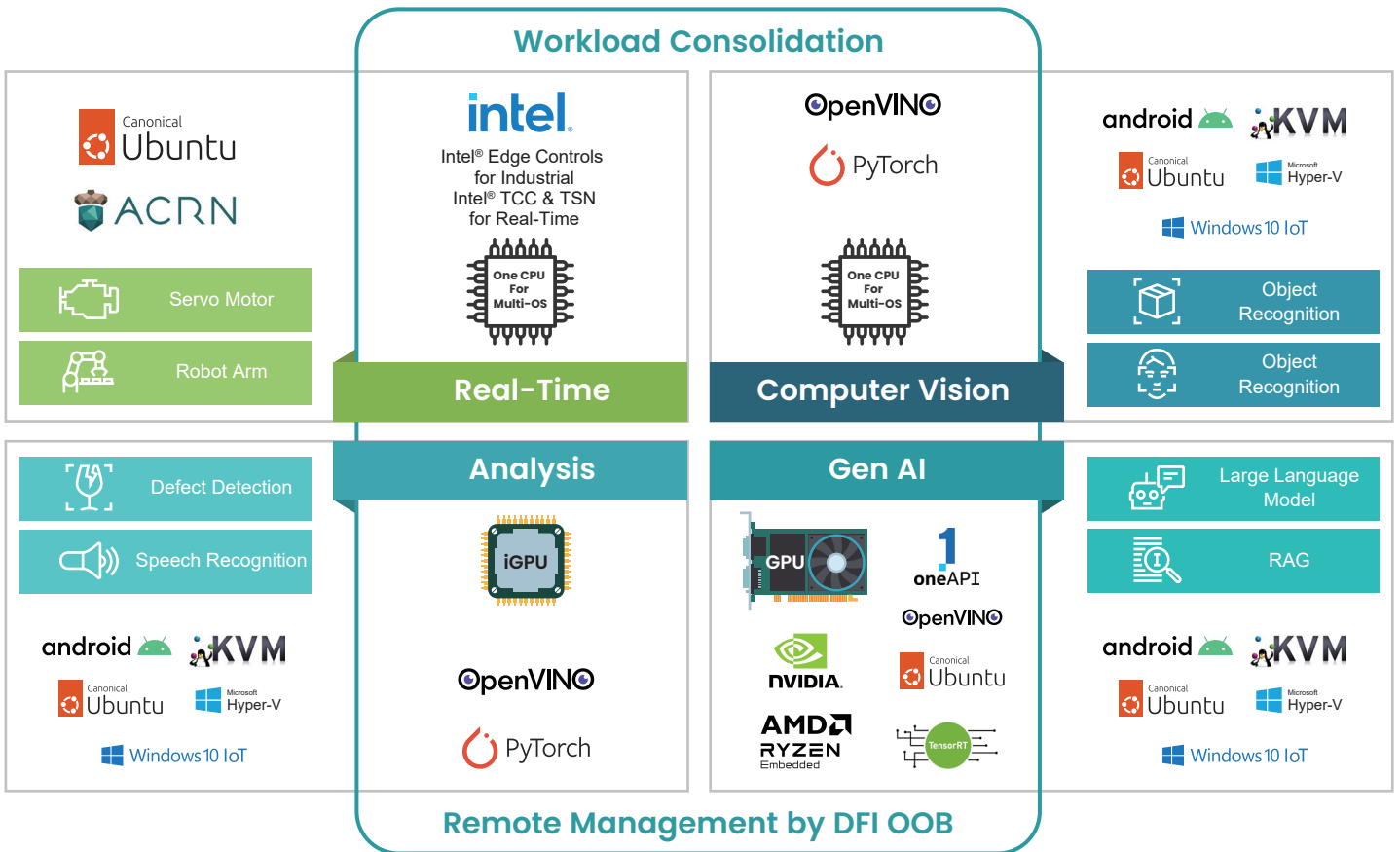
Mini-ITX / Micro-ATX / ATX Motherboard

Industrial Embedded System

Industrial Embedded Board

DFI Workload Platform

DFI's industrial-grade embedded motherboards and computers, enhanced by partner software and solutions, support AI pipelines such as face detection, speech recognition, and LLM-based chatbots, ensuring energy and cost efficiency. These solutions cater to vertical applications in retail, healthcare, transportation, smart factories, hospitality, and more.



DFI Partners



Success Cases

EV Charging Station

E-Scooter Charging | APAC

With advanced AI applications accelerated by Intel Arc GPU for large language models (LLM) on edge computing, EV charging evolves beyond mere refueling, transforming into an interactive, personalized, and revenue-generating solutions.



Self-Service Kiosk

Airport Kiosk | APAC

Leveraging the power of Intel's 14th Generation Core processor, DFI helps customers develop interactive kiosk technologies and solutions that revolutionize business operations and deliver engaging customer experiences.














Factory Automation AMR

AMR with Robotic Arm Control | APAC













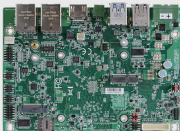
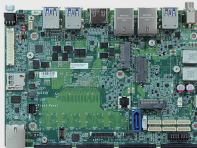
DFI provides real-time computing and out-of-band manageability on the virtualized Intel Atom x7000 platform, ensuring your autonomous mobile robots (AMRs) operate smoothly on the factory floor, in the farm field, or wherever they are deployed.



High-Demands Models

<p>System AI Inference/Training System</p>	<p>System AI Inference/Training System</p>
 <p>X6-MTH-ORN</p> <ul style="list-style-type: none"> Reinforce Nvidia ORIN NX computing power by Intel® Core™ Ultra Processor AI engine NVIDIA Jetson Orin NX, up to 100 TOPS Supports Remote management and OTA by DFI OOB module 4 M.2 B, E, M key expansion slots Optional MXM supported with 3 DP and 1 HDMI ports 4 USB 3.2, 4 RJ45 GbE, micro USB, Serial, CAN bus 	 <p>X6-MTH</p> <ul style="list-style-type: none"> Intel® Core™ Ultra 5/7 Processor (Meteor Lake: U/H-series) Dual Channel DDR5 5600MHz SODIMM up to 64GB Supports 2x GbE, 2x USB 3.2, 2x USB 2.0, RS232/CAN bus 3x B, M, E key M.2 slots Support DFI defined Out of band management Up to 32 TOPS of AI performance
<p>System AI Inference/Training System</p>	<p>System Embedded Fanless PC</p>
 <p>X6-ORN</p> <ul style="list-style-type: none"> Nvidia Jetson ORIN NX, ORIN Nano AI box 6/8-core Arm® Cortex®-A78AE v8.2 64-bit CPU 4x RJ45 GbE ports on Intel i210, optional 2x PoE supported 1x RS232/422/485 and 1 combo RS232/422/485/CAN bus/8bits GPIO port 2x USB 3.2 and 1 micro USB 2.0 1 x M.2 M Key 2280, 1x E key 2230, 1x B key 3042/3052 slot 9-36Vdc power input Out of band remote management supported 	 <p>EC643-RPS</p> <ul style="list-style-type: none"> 12th/13th/14th Generation Intel® Core™ with Intel® R680E Supports DDR5 SODIMM up to 64GB Rich I/O connectivity: 2 2.5GbE, 6 GbE(or 4 GbE, 2 PoE), 10 COM, 5 USB 3.2(Gen2x1), 1 USB Type-C, 1 VGA, 1 HDMI, 1 DP++ Multiple Expansion: 5 M.2 slots, 3 PCIe slot Support 5G Communication Operating Temperature: -20 to 50°C (with 65W CPU) 15-Year CPU Life Cycle Support Until Q4' 36 (Based on Intel IOTG Roadmap)
<p>System Ultra Compact Fanless PC</p>	<p>System Ultra Compact Fanless PC</p>
 <p>EC700-ADN</p> <ul style="list-style-type: none"> Intel® Processor N-series/Atom® Processor X Series On Board OOB built-in Slim and fanless design for limited-space condition Intel TCC within the system On Board DDR5 & eMMC Support 	 <p>EB100-MTU</p> <ul style="list-style-type: none"> Industrial NUC compact system 14th Generation Intel® Ultra 5/ Ultra 7 CPU (12W) Two DDR5 SODIMM, up to 64GB Up to -20°C~50°C operation with passive cooling, optional fan cooling 12VDC power in Ultra compact size(WxHxD):111x51.1x106mm Supports M.2 2230 E-Key/M.2 2280 M-Key Storage: M.2 2280 M-key(NVME) I/O: 2x 2.5GbE (TSN/TCC), 2x USB 3.2, 2x Type-C, 2 HDMI, 1 DB9(RS232/422/485), 1 DB9 (RS232/DIO) Supports M.2 Hailo AI accelerator card(M.2 E key)
<p>System Mini-ITX/ATX System & Chassis</p>	<p>System Mini-ITX/ATX System & Chassis</p>
 <p>RM645-ICX610</p> <ul style="list-style-type: none"> 4U Short-Depth edge server 3rd Gen Intel® Xeon® processors 3 PCIe x16 and 3 PCIe x8 slots support FH/10.5" length cards Up to 8 hot-swappable design available for 2.5" drive bays Rich I/O with 2 GbE, 2 10GbE, 1 RS-232, 4 USB 3.1, 2 USB 2.0 IPMI OOB Remote Management Single Display: VGA resolution up to 1920x1200 @ 60Hz 8 288-pin ECC-RDIMM up to 512GB 	 <p>WM646-ADS</p> <ul style="list-style-type: none"> Compact ATX IPC System, based on DFI ADS630-R680E with Standard Memory Height 4 DDR4 UDIMM up to 128GB Quad Independent Display: VGA + 2 DP++ + HDMI Multiple Expansion: 1 PCIe x16 (Gen5), 4 PCIe x4 (Gen4), 2 PCI, 2 M.2 M key, 1 M.2 E Key Rich I/O: 2 Intel 10GbE, 2 Intel 2.5GbE, USB 3.2 Gen2 (R680E 6x, Q670E 4x), USB 3.2 Gen1 (R680E 4x, Q670E 6x), 3 USB 2.0
<p>Motherboard Mini-ITX</p>	<p>Motherboard Mini-ITX</p>
 <p>RPS101/RPS103</p> <ul style="list-style-type: none"> 14/13/12th Generation Intel® Core™ Processors 2 DDR5 4800MHz SODIMM up to 64GB Supports 4 independent displays: 1 DP++, 1 HDMI, 1 USB Type C, 1 LVDS/eDP, 1 DFI display extension port (DP/HDMI/VGA available) Supports up to 4K resolution Multiple expansion: 1 PCIe x16, 1 M.2 E Key, 1 M.2 M Key, 1 M.2 B Key Rich I/O: 2 Intel 2.5GbE, 2 COM, 6 USB 3.2 Gen2, 4 USB 2.0, 2 SATA 3.0 	 <p>RPS183</p> <ul style="list-style-type: none"> 14th/13th/12th Gen Intel® Core Processors 2 DDR5 SODIMM up to 64GB Multiple Display: 1 DP++(CPU), 1 DP++(MXM), 1 USB Type C(DP Alt-mode), 1 eDP(MXM), 1 internal HDMI(MXM) Support MXM module, with 1 internal HDMI, 1 eDP and 1 external DP++ Multiple Expansion: 1 PCIe x4(side), 1 M.2 M key, 1 M.2 E Key, 1 M.2 B Key Rich I/O: 2 Intel® 2.5GbE, up to 4 USB 3.2 Type A, up to 1 USB Type C Wide Range power input 19~24V
<p>Motherboard microATX</p>	<p>Motherboard ATX</p>
 <p>RAP310-B650</p> <ul style="list-style-type: none"> AMD® Ryzen™ 7000 Series with AMD B650 chipset 4 DDR5 UDIMM up to 128GB Triple displays: 1 VGA, 1 DP++, 1 HDMI Supports 4K resolution Multiple expansion: 2 PCIe x16, 2 PCIe x4, 1 M.2 E key, 1 M.2 M key, 4 SATA 3.0 Rich I/O: 2 Intel 2.5GbE, 4 COM, 6 USB 3.2 Gen2, 2 USB 3.2 Gen1, 6 USB 2.0 	 <p>RPS630-R680E/Q670E</p> <ul style="list-style-type: none"> 14th/13th/12th Gen Intel® Core Processors 4 DDR5 UDIMM up to 192GB Quad Displays: VGA, 2 DP++, HDMI Supports 4K resolution Multiple Expansion: 2 PCIe x16, 4 PCIe x4, 1 PCI, 2 M.2 M key, 1 M.2 E Key, 1 M.2 A Key Rich I/O: 4 Intel 2.5GbE, 6 COM, 4 USB 3.2 Gen2, 6 USB 3.2 Gen1, 3 USB 2.0
<p>Motherboard ATX</p>	<p>Motherboard ATX</p>
 <p>ADS630-R680E/Q670E</p> <ul style="list-style-type: none"> 14th/13th/12th Gen Intel® Core Processors 4 DDR4 UDIMM up to 128GB Quad Displays: VGA + 2 x DP++ + HDMI Supports 4K resolution Multiple Expansion: 1 PCIe x16(Gen 5), 4 PCIe x4(Gen 4), 2 PCI, 2 M.2 M key, 1 M.2 E Key Rich I/O: 2 Intel 10GbE, 2 Intel 2.5GbE, USB 3.2 Gen 2 (R680E 6x, Q670E 4x), USB 3.2 Gen1 (R680E 4x, Q670E 6x), USB 2.0 3x 	 <p>ICX610-C621A</p> <ul style="list-style-type: none"> 3rd Gen Intel® Xeon® Scalable Processor Family 8 ECC-RDIMM up to 512GB 2 x 10GbE IPMI OOB Remote Management Single Display: VGA resolution up to 1920x1200 @ 60Hz Multiple Expansion: 3 PCIe x16, 2 PCIe x8, 1 x M.2 M key Rich I/O: 2 Intel GbE, 1 Dedicated IPMI, 2 COM, 6 USB 3.1 Gen1, 5 USB 2.0



<p>System-on-Module COMe Mini</p>	<p>System-on-Module COMe Mini</p>
 <p>ASL9A2</p> <ul style="list-style-type: none"> Intel® Atom® Processor Amston Lake Series Dual Channel LPDDR5 4800MHz up to 16GB 1 LVDS/eDP, 1 DDI (HDMI/DP++) : Supports dual displays: DDI + LVDS/eDP Multiple expansions: 4 PCIe x1, 1 SMBus, 1 I2C, 1 eMMC Rich I/O: 2 USB 3.1, 8 USB 2.0 High Speed Ethernet: Supports 100M/1000M/2.5Gbps 	 <p>COMING SOON MTU9A2</p> <ul style="list-style-type: none"> Intel® Core™ Ultra Processor (Meteor Lake: U-series) Single Channel LPDDR5 7467MHz up to 16GB Dual Displays: 1 DDI + 1 LVDS/eDP Supports 4K / 2K resolution Multiple Expansion: 4 PCIe x1, 1 I2C, 1 SMBus, 1 x LPC/eSPI, 2 x UART Rich I/O: 1 Intel 2.5GbE, 2 USB 3.2, 8 USB 2.0, 2 SATA 3.0
<p>System-on-Module COMe Compact</p>	<p>System-on-Module COMe Basic</p>
 <p>MTH968</p> <ul style="list-style-type: none"> Intel® Core™ Ultra Processor (Meteor Lake: U/H-series) Dual Channel DDR5 5600MHz SODIMM up to 64GB Multiple Displays: 1 VGA + 1 LVDS/eDP + 3 DDI Supports 4K / 2K resolution Multiple Expansion: 8 PCIe x1, 2 PCIe x4, 1 PCIe x8, 1 I2C, 1 SMBus, 1 LPC/eSPI, 2 UART Rich I/O: 1 Intel 2.5GbE, 2 USB 4.0, 3 USB 3.2, 8 USB 2.0, 2 SATA 3.0 	 <p>ICD970</p> <ul style="list-style-type: none"> 3rd Gen Intel® Xeon® Processor D-1700 Family Default 2 260-pin DDR4 2666 SO-DIMM, dual channel mode up to 64GB, 3rd DIMM by Support extended operating temperature: -40 to 85°C 10GBASE-KR: Support up to 4 x 10GbE Mac ports Multiple Expansion: 1 PCIe x16 (Gen4), 2 PCIe x8 (Gen3), 1 SMBus, 1 I2C, 1 LPC, 2 UART (TX/RX) Rich I/O: 2 Intel GbE, 4 USB 3.0, 4 USB 2.0, 2 SATA 3.0
<p>System-on-Module COM HPC</p>	<p>System-on-Module Qseven</p>
 <p>RPS9HC-R680E/ Q670E/H610E</p> <ul style="list-style-type: none"> 14th/13th Gen Intel® Core™ with Intel® R680E/Q670E/H610E Chipset 4 DDR5 SODIMM 3600MHz up to 192GB Quad Displays: eDP + 3 DDI DDI supports up to 8K Multiple Expansion: 1 PCIe x16 (Gen5), 4 PCIe x4 (Gen4), 2 PCIe x4 (Gen3), 2 PCIe x1 (Gen3) Rich I/O: 2 Intel 2.5GbE, 6 USB 3.2 Gen2, 8 USB 2.0 	 <p>RK701</p> <ul style="list-style-type: none"> 2GB/4GB/8GB DDR4 Memory Down Supports 4K / 2K resolution 1 eDP/LVDS + 1 DP/TMDS Multiple expansions: 2 PCIe 3.0, 1 PCIe 2.0 Rich I/O: 1 Realtek GbE, 1 USB 3.2, 4 USB 2.0
<p>Single Board Computer 1.8"</p>	<p>Single Board Computer 1.8"</p>
 <p>AIMF51</p> <ul style="list-style-type: none"> Qualcomm® QCS8550 high-level platform Target on edge AI box, AIoT application Thin client concept and ruggedize Optimized AI architecture (48 INT8, 12 FP16 TOPs) Supports CPU Life Cycle Until 2033 	 <p>PCSF51</p> <ul style="list-style-type: none"> AMD Ryzen™ Embedded R2000 Series - Picasso Small form factor 1.8" SBC for space-limited applications Single Channel DDR4 Memory Down up to 4GB/8GB HDMI 1.4 resolution supports up to 4096 x 2160 @ 24Hz Storage up to 128GB: eMMC 32GB/ 64GB/ 128GB 10-Year CPU Life Cycle Support Until Q2' 32 (Based on AMD Roadmap)
<p>Single Board Computer 2.5"</p>	<p>Single Board Computer 2.5"</p>
 <p>QCS051</p> <ul style="list-style-type: none"> Qualcomm QCS6490 high-level platform Target on AMR, box PC application Thin client concept and ruggedize 2 M.2 Expansions: 1 M.2 E key 2230, 1 M.2 B key 3052 Supports CPU Life Cycle Until 2036 	 <p>RPP051</p> <ul style="list-style-type: none"> Small form factor 2.5" Pico-ITX for space-limited applications 13th Generation Intel® Core™ Processors 1 DDR5 4800MHz SODIMM up to 32GB Supports 4K/2K resolution Dual Independent Displays: DP+++ + eDP Multiple Expansion: 1 M.2 E key, 2 M.2 B key Rich I/O: 1 Intel 2.5G LAN, 1 COM, 2 USB 3.1 Gen 2, 2 USB 2.0
<p>Single Board Computer 2.5"</p>	<p>Single Board Computer 3.5"</p>
 <p>M93053</p> <ul style="list-style-type: none"> NXP i.MX93 platform, target on entry level application Wide Voltage support 9~36VDC Two GbE Lan for automation application CAN bus support M.2 3042 support 	 <p>ADN553</p> <ul style="list-style-type: none"> Intel® Atom® Alder Lake-N Processors 3.5" SBC 1 DDR5 SO-DIMM 4K High Resolution: Supports 4K/ 2K resolution Triple Display: 1 HDMI, 1 Type-C DP Alt. Mode, 1 LVDS/eDP Rich I/O Connectivity: 3 2.5GbE LAN, 4 USB 3.2, 2 USB 2.0, 1 SATA Multiple Expansion: 1 M.2 M Key, 1 M.2 B Key, 1 M.2 E Key
<p>Single Board Computer 3.5"</p>	<p>Single Board Computer 4"</p>
 <p>M8MP553</p> <ul style="list-style-type: none"> ARM® i.Mx8M plus-based Processor for 30% performance enhancement Industry-Leading Wide Voltage Support 9 to 36V Ultra-High-Speed Connectivity for 4G/5G Edge Gateway Outstanding Graphic Performance, supports LVDS and HDMI with dual display CAN bus for automation equipment integration 1 M.2 2230 E key, 1 3052 B key 15-Year CPU Life Cycle Support Until Q1' 36 (Based on NXP Roadmap) 	 <p>MTH253</p> <ul style="list-style-type: none"> Intel® Core™ Ultra Processor 4" SBC On Board OOB built-in (Opt.) LPDDR5x-7500 memory down Multiple Displays: 1 HDMI, 1 dual channel LVDS, 1 Type-C DP Alt. Mode Multiple Expansion: 1 M.2 M Key, 1 M.2 B Key, 1 M.2 E Key Rich I/O: 2 Intel 2.5GbE, 1 Intel GbE, 4 COM, 4 USB 3.2, 1 USB 2.0, 1 USB Type-C

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DFI Desire
For
Innovation

Founded in 1981, DFI is a global leading provider of high-performance computing technology across multiple embedded industries. With its innovative design and premium quality management system, DFI's industrial-grade solutions enable customers to optimize their equipment and ensure high reliability, long-term life cycle, and 24/7 durability in a breadth of markets including Industrial Automation, Medical, Gaming, Transportation, Energy, Mission-Critical, and Intelligent Retail.